BIPMIC® – Cascadable Silicon Bipolar Amplifier

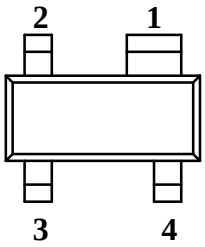
Electrostatic sensitive device.
Observe precautions for handling.

Applications

General purpose for narrow and broad band IF and RF amplifiers in commercial and industrial applications with low power consumption. This allows to build amplifiers with minimal external circuitry, thus providing a simple, cost effective way to achieve low level amplification, for example in cordless phones.

Features

- Broadband amplification
- Low operating voltage
- Low operating current
- High gain (8.5dB at 900MHz and 50 Ω
- Low cost surface mount plastic package
- Few external components



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S860T Marking: 860
Plastic case (SOT 143)
1 = RF–output; 2 = Ground; 3 = RF–input; 4 = Ground

Absolute Maximum Ratings

Parameters	Symbol	Value	Unit
Device current	I_{bias}	4	mA
RF Input power	P_{in}	0	dBm
Total power dissipation $T_{amb} \leq 146°C$	P_{tot}	8	mW
Junction temperature	T_j	150	°C
Storage temperature range	T_{stg}	–65 to +150	°C

Maximum Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient on glass fibre printed board (25 x 20 x l.5) mm^3 plated with 35 µm Cu	R_{thJA}	450	K/W

Electrical AC Characteristics

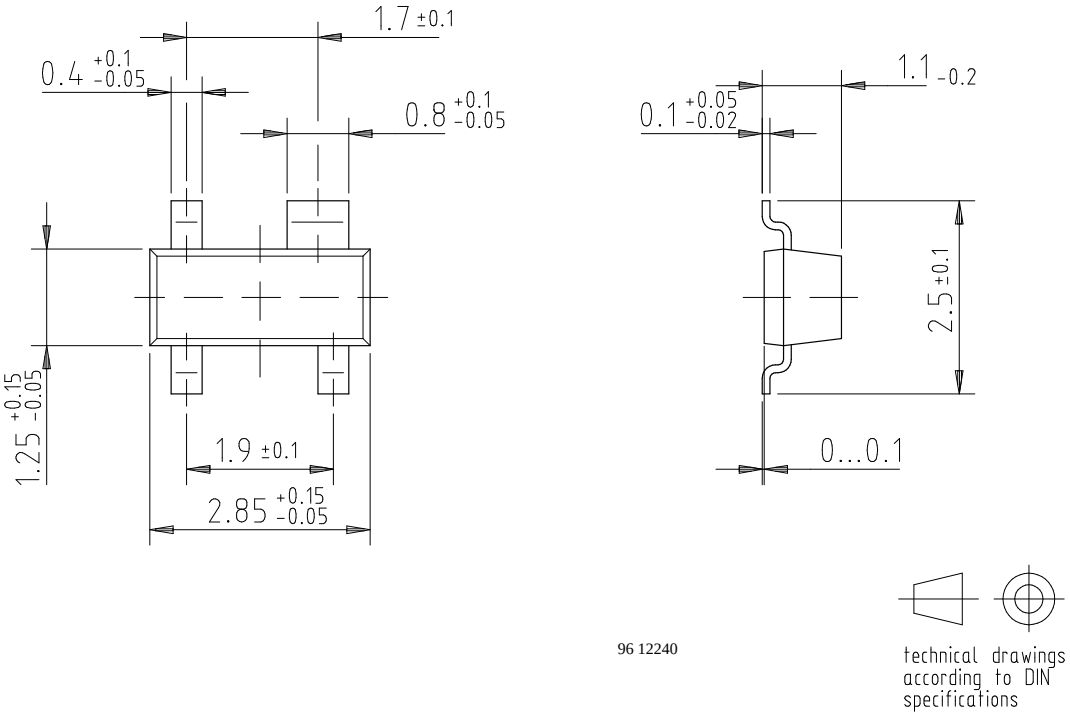
I_{bias} = 3 mA, Z_0 = 50 Ω, T_{amb} = 25°C

Parameters / Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Power gain					
f = 900 MHz	G_p	6	8.5		dB
f = 1.9 GHz	G_p	5	7.5		dB
3 dB bandwidth	f_{3dB}		2.5		GHz
Noise figure					
f = 900 MHz	F		5.5		dB
f = 1.9 GHz	F		6.5		dB
Intermodulation distortion					
7 mV input voltage, f = 900 MHz	IM_3		40		dB
f = 1.9 GHz	IM_3		45		dB
Device voltage	V_d		1.8		V

Typical Source S-Parameters
V_{cc} = 2.4 V, R_{bias} = 200 Ω, Z_0 = 50 Ω

f/MHz	S_{11}		S_{21}		S_{12}		S_{22}	
	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG	LOG MAG	ANG
	dB	deg	dB	deg	dB	deg	dB	deg
100	–2.28	–2.7	7.78	174.9	–20.37	19.2	–2.06	–11.3
200	–2.34	–5.4	7.72	170.2	–20.00	15.3	–2.54	–10.6
300	–2.40	–8.1	7.69	165.6	–19.49	16.1	–2.86	–12.4
400	–2.46	–10.3	7.64	160.4	–19.28	18.9	–2.88	–14.5
500	–2.57	–13.0	7.63	155.7	–18.93	22.0	–2.84	–17.6
600	–2.66	–15.5	7.59	150.7	–18.39	25.4	–2.84	–21.4
700	–2.71	–17.7	7.49	146.6	–17.63	27.0	–3.01	–25.7
800	–2.75	–20.2	7.41	141.9	–16.93	27.1	–3.40	–29.7
900	–2.85	–22.5	7.38	137.2	–17.21	26.0	–3.45	–26.4
1000	–2.93	–24.9	7.33	132.9	–16.42	27.6	–3.62	–32.3
1100	–3.05	–27.1	7.24	128.6	–15.89	29.2	–3.55	–36.3
1200	–3.18	–29.7	7.10	124.4	–15.36	29.2	–3.67	–39.9
1300	–3.28	–32.6	7.08	120.1	–14.63	30.4	–3.53	–45.5
1400	–3.37	–35.0	7.03	116.4	–14.18	27.5	–4.22	–49.1
1500	–3.54	–37.4	6.87	112.1	–13.88	26.0	–4.62	–51.5
1600	–3.63	–40.4	6.91	108.2	–13.64	24.4	–5.03	–53.6
1700	–3.75	–43.1	6.82	104.5	–13.36	23.4	–5.24	–55.4
1800	–3.90	–46.1	6.76	100.8	–13.03	23.0	–5.26	–58.0
1900	–4.10	–49.0	6.78	96.5	–12.66	22.3	–5.40	–61.9
2000	–4.24	–52.2	6.73	93.0	–12.35	20.6	–5.75	–65.3
2100	–4.35	–55.7	6.65	89.1	–12.14	19.0	–6.09	–67.7
2200	–4.54	–59.1	6.64	85.4	–11.98	17.7	–6.34	–69.9
2300	–4.81	–62.2	6.46	81.8	–11.79	17.1	–6.40	–72.0
2400	–4.75	–65.7	6.61	78.5	–11.35	16.6	–6.31	–76.7
2400	–5.02	–72.4	6.74	74.4	–10.86	13.3	–6.69	–82.9
2600	–5.61	–75.7	6.61	69.5	–10.64	10.7	–7.13	–87.0
2700	–6.05	–80.4	6.54	65.3	–10.54	8.6	–7.60	–89.9
2800	–6.50	–84.4	6.56	61.8	–10.48	6.3	–8.10	–92.8
2900	–7.02	–89.6	6.33	57.3	–10.42	3.9	–8.60	–96.0
3000	–7.45	–94.6	6.31	53.0	–10.38	1.8	–9.11	–99.0

Dimensions in mm



Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements.

2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively

2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA

3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.
Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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